



### Introduction

FA series probe bench is a measuring equipment specially designed for failure analysis laboratory. It has optical and laser characteristics, stable equipment structure, excellent system performance, ergonomic design, convenient operation, support multi-function upgrade, and rich and complete product functions.

### Application Direction

Chip failure analysis at room temperature and high temperature, RF component failure analysis, MATERIAL/-component IV/CV characteristic test and failure analysis, chip internal circuit/electrode /PAD test, IC/ panel internal circuit modification/de-lamination

### Product Feature

- Large handle drive, no clearance movement
- Ergonomic design, convenient and comfortable to operate
- Multi-band laser application, fast switching and accurate cutting
- Compatible with high power metallographic microscope for fine adjustment and movement
- No backtrip difference design, accurate positioning
- The air cooling structure is compact and requires no maintenance
- High precision system, laser machining accuracy up to 1\*1um
- Leading internal anti - shock system device, more stable operation

## Specification

Model	FA-8	FA-8-SC	
Dimension	L: 960mm*W: 850mm*H: 1500mm	L: 880mm*W: 860mm*H: 1550mm	
Weight (about)	260KG	280KG	
Electricity Demand	220VC, 50~60Hz		
Chuck	Size & Rotation angle	8", 360° Rotation	
	X-Y travel range	8" * 8"	
	Moving resolution	1µm	
	Sample fixed mode	Vacuum adsorption	Vacuum adsorption
	Temperature control range	-	- 80~200°C
	Quick pull out	-	yes
	Electrical design	Chuck Surface is Electrical Floating with Banana plug adapter, can be used as a backside electrode.	
Platen	Specification	U shape Platen, 10 micropositioners available	O shape Platen, 12 micropositioners available
	Travel & adjustment mode	Platen can be quickly lifted up and down 6mm with automatic locking function,Platen can be fine tuned up and down 25mm precisely with 1µm resolution	
Microscope	Travel range	X-Y: 2" * 2", Z: 50.8mm	X-Y: 1" * 1", Z: 50.8mm
	Resolution	1µm	
	Magnification	20 ~ 4000X	
	Operation of lens switching	Fast tilting	Pneumatic lifting
	CCD pixels	50W (Analog) / 200W (Digital) / 500W (Digital)	
Laser	Wavelength	Wavelength selectable: 1064/532/355/266nm	
	Output power	0~2.2mJ/pulse	
	Micromachining capability	Machinable material: Cr / Al / ITO / Ni / TFT / RGB / Poly Silicon / Mo / SiN / CF internal impurity etc.	
	Precision	Minimum Machinable size is 1*1µm (when using 100X lens)	
	Cooling mode	Air-cooled laser or Water cooled laser	
Micropositioner	X-Y-Z moving range	12mm-12mm-12mm / 8mm-8mm-8mm	
	Mechanical resolution	2µm / 0.7µm / 0.1µm	
	Current leakage accuracy	10pA / 100fA (with Shielding Box)	
	Cable connectors	Banana head / Crocodile clip / Coaxial / Triaxial	
Optional Accessories	Chuck fast pull-out mechanism		
	Hot spot detection by liquid crystal package		
	High voltage / high current test suite		
	Hot chuck		
	Shielding box		
	Special adapter		
	Vibration free table		
	Gold-plated chuck		
	Coaxial / Triaxial chuck		
	Chuck Z quickly lifting and lowering and fine adjustment selection		
	Light intensity / wavelength test		
	RF test accessories		
	Active probe		
	Low current / Capacitance test		
	Fixture for Fibre optic coupler test		
Fixture of Packaged IC test accessory			
Fixture of PCB test accessory			
Special Custom design			